



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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SEAF-20-01-L-04-2-RA-GP-TR



SEAF-20-01-L-06-2-RA-GP-TR

**SEAF-RA SERIES**

**(1.27 mm) .050"**

# HI-DENSITY RIGHT-ANGLE OPEN-PIN-FIELD

**SPECIFICATIONS**

For complete specifications and recommended PCB layouts see [www.samtec.com?SEAF-RA](http://www.samtec.com?SEAF-RA)

**Insulator Material:**

Black LCP

**Contact Material:**

Copper Alloy

**Current Rating:**

2.1 A per pin

(4 adjacent pins powered)

**Operating Temp Range:**

-55 °C to +125 °C

**Plating:**

Au or Sn over

50 μ" (1.27 μm) Ni

**Contact Resistance:**

17.1 mΩ max

**Working Voltage:**

280 VAC

**Mated Cycles:**

100

**RoHS Compliant:**

Yes

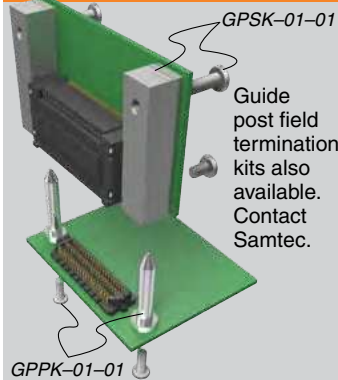
**Lead-Free Solderable:**

Yes

**Board Mates:**  
SEAM, SEAMP

**Cable Mates:**  
SEAC

**OTHER SOLUTIONS**



Guide post field termination kits also available. Contact Samtec.

Up to 500 pins



Solder charge terminations

Optional guide post holes

Low insertion/ extraction forces

**HIGH-SPEED CHANNEL PERFORMANCE**

**SEAF-RA/SEAM-RA**

Rating based on Samtec reference channel. For full SI performance data visit [Samtec.com](http://Samtec.com) or contact [SIG@samtec.com](mailto:SIG@samtec.com)

**25**  
Gbps

**RECOGNITIONS**

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



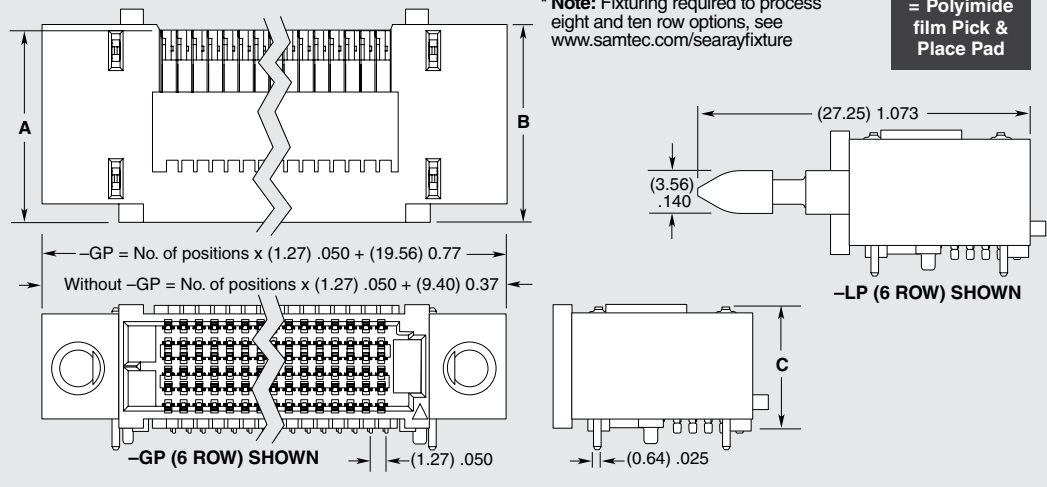
SEAF	NO. PINS PER ROW	01	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	RA	OPTION	TR
	-20, -30, -40, -50		-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail  -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-04 = Four Rows -06 = Six Rows -08* = Eight Rows -10* = Ten Rows	-1 = Tin/Lead Alloy Solder Charge -2 = Lead-Free Solder Charge		-GP = Guide Post Hole -LP = Latch Post (06 row 30 positions only) (Mates to SEAC Series) -K = Polyimide film Pick & Place Pad	-TR = Tape & Reel

NO. OF ROWS	A	B	C
-04	(13.26) .522	(13.77) .542	(7.91) .311
-06	(15.80) .622	(16.31) .642	(10.45) .411
-08	(18.34) .722	(18.85) .742	(12.99) .511
-10	(20.88) .822	(21.39) .842	(15.53) .611

\* Note: Fixturing required to process eight and ten row options, see [www.samtec.com/searayfixture](http://www.samtec.com/searayfixture)

**ALSO AVAILABLE (MOQ Required)**

- Other platings
- Contact Samtec.



Note: Some sizes, styles and options are non-standard, non-returnable.